# Field Stop Trench IGBT 40 A, 650 V

# AFGHL40T65SQ

Using the novel field stop 4th generation high speed IGBT technology. AFGHL40T65SQ which is AEC Q101 qualified offers the optimum performance for both hard and soft switching topology in automotive application. It is a stand–alone IGBT.

#### **Features**

- AEC-Q101 Qualified
- Maximum Junction Temperature:  $T_J = 175^{\circ}C$
- Positive Temperature Co-efficient for Easy Parallel Operating
- High Current Capability
- Low Saturation Voltage:  $V_{CE(Sat)} = 1.6 \text{ V (Typ.)} @ I_C = 40 \text{ A}$
- 100% of the Parts are Tested for I<sub>LM</sub> (Note 2)
- Fast Switching
- Tight Parameter Distribution
- RoHS Compliant

## **Typical Applications**

- Automotive HEV-EV Onboard Chargers
- Automotive HEV-EV DC-DC Converters
- Totem Pole Bridgeless PFC
- PTC

### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-to-Emitter Voltage	V <sub>CES</sub>	650	V
Gate-to-Emitter Voltage Transient Gate-to-Emitter Voltage	V <sub>GES</sub>	±20 ±30	٧
Collector Current (Note 1) @ $T_C = 25^{\circ}C$ @ $T_C = 100^{\circ}C$	I <sub>C</sub>	80 40	Α
Pulsed Collector Current (Note 2)	I <sub>LM</sub>	160	Α
Pulsed Collector Current (Note 3)	I <sub>CM</sub>	160	Α
Maximum Power Dissipation @ $T_C = 25^{\circ}C$ @ $T_C = 100^{\circ}C$	P <sub>D</sub>	239 119	W
Operating Junction / Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	–55 to +175	°C
Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5 seconds	TL	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

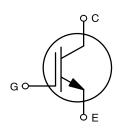
- 1. Value limit by bond wire
- 2.  $V_{CC}$  = 400 V,  $V_{GE}$  = 15 V,  $I_{C}$  = 160 A,  $R_{G}$  = 15  $\Omega$ , Inductive Load
- 3. Repetitive Rating: pulse width limited by max. Junction temperature

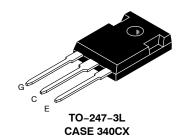


# ON Semiconductor®

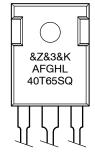
www.onsemi.com

40 A, 650 V V<sub>CESat</sub> = 1.6 V





## **MARKING DIAGRAM**



&Z = Assembly Plant Code &3 = 3-Digit Date Code

AFGHL40T65SQ = Specific Device Code

&K = 2-Digit Lot Traceability Code

## **ORDERING INFORMATION**

Device	Package	Shipping
AFGHL40T65SQ	TO-247-3L	30 Units / Rail

## THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ hetaJC}$	0.63	°C/W
Thermal resistance junction-to-ambient	$R_{ hetaJA}$	40	°C/W

# **ELECTRICAL CHARACTERISTICS** (T<sub>.I</sub> = 25°C unless otherwise noted)

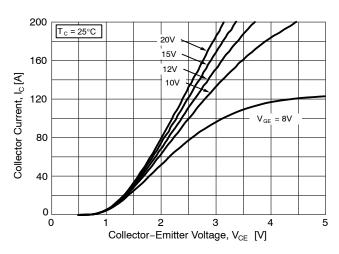
Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS			•	•	•	
Collector-emitter breakdown voltage, gate-emitter short-circuited	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1 mA	BV <sub>CES</sub>	650	-	_	V
Temperature Coefficient of Breakdown Voltage	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1 mA	ΔBV <sub>CES</sub>	-	0.6	-	V/°C
Collector-emitter cut-off current, gate-emitter short-circuited	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 650 V	I <sub>CES</sub>	-	-	250	μΑ
Gate leakage current, collector- emitter short-circuited	V <sub>GE</sub> = 20 V, V <sub>CE</sub> = 0 V	I <sub>GES</sub>	-	-	±400	nA
ON CHARACTERISTICS						
Gate-emitter threshold voltage	$V_{GE} = V_{CE}$ , $I_C = 40 \text{ mA}$	V <sub>GE(th)</sub>	3.4	4.9	6.4	V
Collector-emitter saturation voltage	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 40 A V <sub>GE</sub> = 15 V, I <sub>C</sub> = 40 A, T <sub>J</sub> = 175°C	V <sub>CE(sat)</sub>	-	1.6 1.95	2.1 -	V
DYNAMIC CHARACTERISTICS			•		•	
Input capacitance	V <sub>CE</sub> = 30 V,	C <sub>ies</sub>	-	2312	-	pF
Output capacitance	V <sub>GE</sub> = 0 V, f = 1 MHz	C <sub>oes</sub>	-	30	-	-
Reverse transfer capacitance		C <sub>res</sub>	-	8	-	
Gate charge total	V <sub>CE</sub> = 400 V,	Qg	-	68	-	nC
Gate-to-emitter charge	I <sub>C</sub> = 40 A, V <sub>GE</sub> = 15 V	Q <sub>ge</sub>	-	13	-	
Gate-to-collector charge	1	Q <sub>gc</sub>	-	16	-	
SWITCHING CHARACTERISTICS, INC	DUCTIVE LOAD		•	•	•	
Turn-on delay time	T <sub>C</sub> = 25°C,	t <sub>d(on)</sub>	-	15	-	ns
Rise time	$V_{CC} = 400 \text{ V},$ $I_{C} = 20 \text{ A},$	t <sub>r</sub>	-	10	-	
Turn-off delay time	$\overline{R}_G = 6 \Omega$ , $V_{GE} = 15 V$ ,	t <sub>d(off)</sub>	-	70	-	
Fall time	Inductive Load,	t <sub>f</sub>	-	3	-	
Turn-on switching loss	FWD: AFGHL40T65SQD	E <sub>on</sub>	-	0.25	-	mJ
Turn-off switching loss	1	E <sub>off</sub>	-	0.09	-	
Total switching loss		E <sub>ts</sub>	-	0.34	-	
Turn-on delay time	T <sub>C</sub> = 25°C,	t <sub>d(on)</sub>	-	17	-	ns
Rise time	$V_{CC} = 400 \text{ V},$ $I_{C} = 40 \text{ A},$	t <sub>r</sub>	-	22	-	
Turn-off delay time	$R_G=6\Omega, \ V_{GE}=15V, \ Inductive Load,$	t <sub>d(off)</sub>	-	67	-	
Fall time		t <sub>f</sub>	-	31	-	
Turn-on switching loss	FWD: AFGHL40T65SQD	E <sub>on</sub>	-	0.75	-	mJ
Turn-off switching loss	1	E <sub>off</sub>	-	0.29	-	
Total switching loss	1	E <sub>ts</sub>	-	1.04	-	

# **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise noted) (Continued)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
SWITCHING CHARACTERISTICS, II	IDUCTIVE LOAD					
Turn-on delay time	T <sub>J</sub> = 175°C,	t <sub>d(on)</sub>	-	14	_	ns
Rise time	$V_{CC} = 400 \text{ V},$ $I_{C} = 20 \text{ A},$	t <sub>r</sub>	-	12	-	
Turn-off delay time	$R_G = 6 \Omega,$ $V_{GE} = 15 V,$	t <sub>d(off)</sub>	-	81	-	
Fall time	Inductive Load, FWD: AFGHL40T65SQD	t <sub>f</sub>	-	7	-	
Turn-on switching loss	- TWB. AI GIIL401033QB	E <sub>on</sub>	-	0.46	-	mJ
Turn-off switching loss		E <sub>off</sub>	-	0.22	-	1
Total switching loss		E <sub>ts</sub>	-	0.68	-	1
Turn-on delay time	T <sub>J</sub> = 175°C,	t <sub>d(on)</sub>	-	16	-	ns
Rise time	$V_{CC} = 400 \text{ V},$ $I_{C} = 40 \text{ A},$	t <sub>r</sub>	-	25	-	1
Turn-off delay time	$R_{G}$ = 6 $\Omega$ , $V_{GE}$ = 15 V, Inductive Load, FWD: AFGHL40T65SQD	t <sub>d(off)</sub>	-	75	-	
Fall time		t <sub>f</sub>	-	38	-	1
Turn-on switching loss		E <sub>on</sub>	-	1.06	-	mJ
Turn-off switching loss		E <sub>off</sub>	_	0.47	-	1
Total switching loss		E <sub>ts</sub>	-	1.53	-	1

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## **TYPICAL CHARACTERISTICS**



**Figure 1. Typical Output Characteristics** 

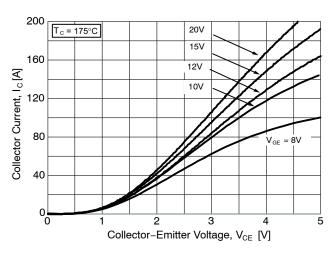


Figure 2. Typical Output Characteristics

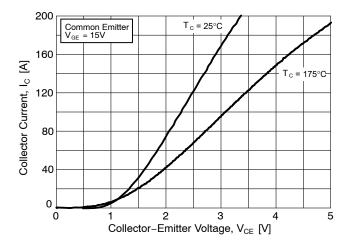


Figure 3. Typical Saturation Voltage

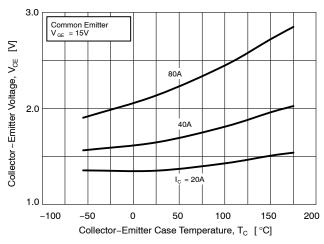


Figure 4. Saturation Voltage vs. Case Temperature

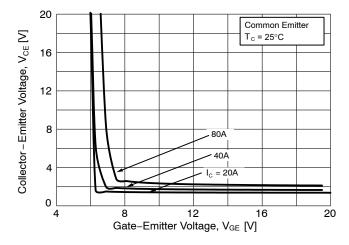


Figure 5. Saturation Voltage vs. V<sub>GE</sub>

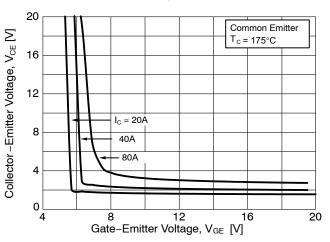
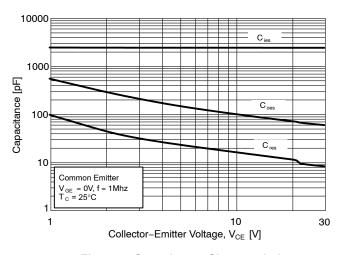


Figure 6. Saturation Voltage vs. V<sub>GE</sub>

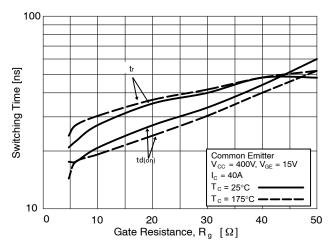
## **TYPICAL CHARACTERISTICS**



Common Emitter T <sub>C</sub> = 25°C 300V ∑ 12 400V V <sub>CC</sub> = 200V Gate - Emitter Voltage, VGE 9 6 3 0 25 50 75 100 Gate Charge, Qg [nC]

Figure 7. Capacitance Characteristics

Figure 8. Gate Charge



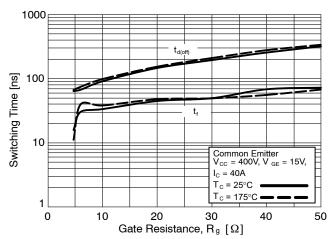
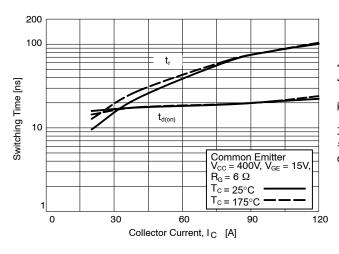


Figure 9. Turn-On Characteristics vs. Gate Resistance

Figure 10. Turn-Off Characteristics vs. Gate Resistance



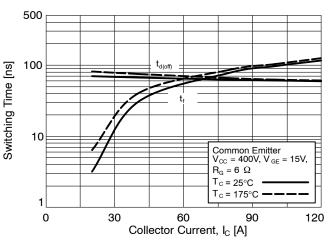
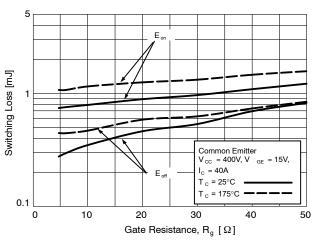


Figure 11. Turn-On Characteristics vs.
Collector Current

Figure 12. Turn-Off Characteristics vs.
Collector Current

# **TYPICAL CHARACTERISTICS**



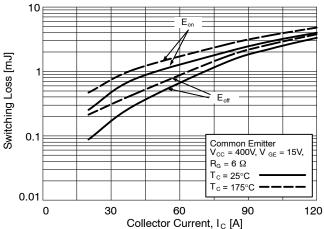


Figure 13. Switching Loss vs. Gate Resistance

Figure 14. Switching Loss vs. Collector Current

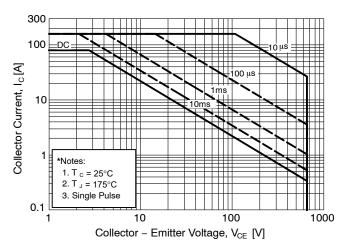


Figure 15. SOA Characteristics

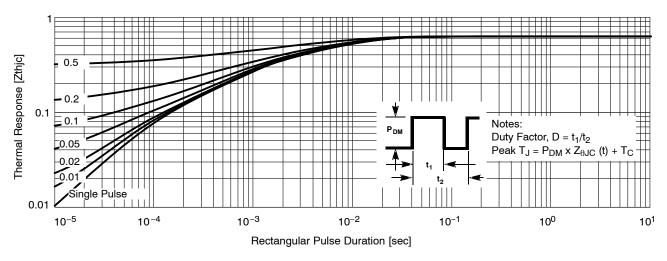
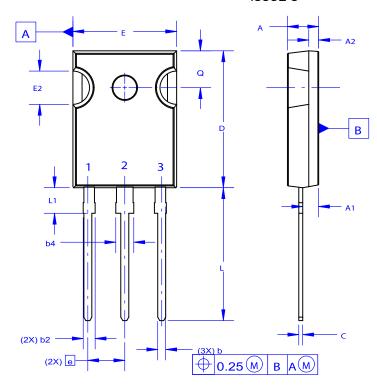


Figure 16. transient Thermal Impedance of IGBT

## **PACKAGE DIMENSIONS**

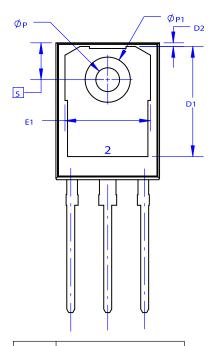
TO-247-3LD CASE 340CX ISSUE O



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

  B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
  E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.



DIM	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	4.58	4.70	4.82	
<b>A</b> 1	2.20	2.40	2.60	
A2	1.40	1.50	1.60	
D	20.32	20.57	20.82	
Е	15.37	15.62	15.87	
E2	4.96	5.08	5.20	
е	?	5.56	~	
L	19.75	20.00	20.25	
L1	3.69	3.81	3.93	
ØΡ	3.51	3.58	3.65	
Q	5.34	5.46	5.58	
S	5.34	5.46	5.58	
b	1.17	1.26	1.35	
b2	1.53	1.65	1.77	
b4	2.42	2.54	2.66	
С	0.51	0.61	0.71	
D1	13.08	~	~	
D2	0.51	0.93	1.35	
E1	12.81	~	~	
ØP1	6.60	6.80	7.00	

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